

FAQs for AIoT

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Why we need AIoT? What are functions of AIoT?

What is APC? How to do the retrain?

How to do the transfer learning?

How much data is required? What is soft sensor?

What are sensor resolutions?

How do deploy the model? What is PdM?

What kind of sensors? Why we need AI?
How to monitor the model?

What are the key features? How to decide the NN?

How to build the system?

Why we need IoT? How many models build?

What

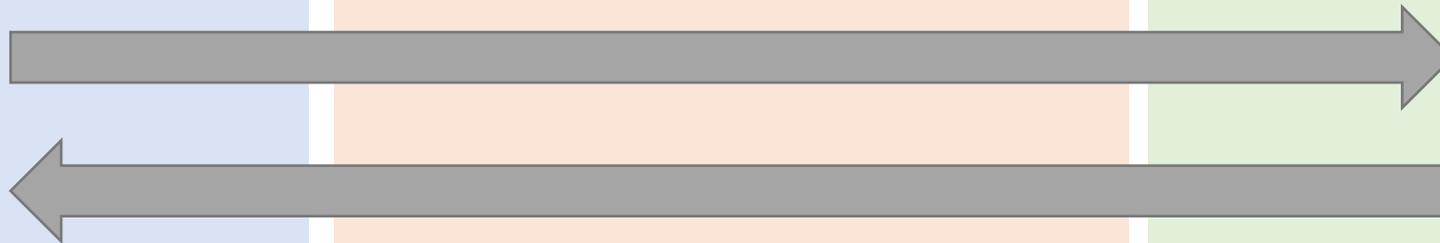
What kind of sensors?
What are sensor resolutions?
What is APC?
What are functions of AIoT?
What is soft sensor?
What is PdM?
What are the key features?

How

How much data is required?
How to build the system?
How many models build?
How to monitor the model?
How do deploy the model?
How to do the retrain?
How to decide the NN?
How to do transfer learning?

Why

Why we need AI?
Why we need IoT?
Why we need AIoT?

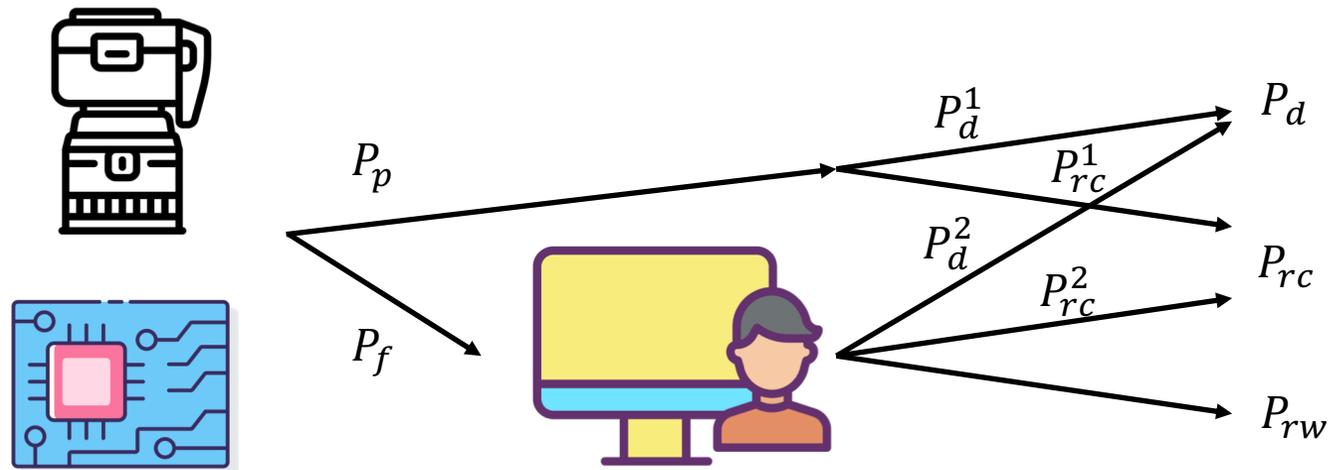


Why We need AIoT?

- Top Down View
 - Corporate strategy, infrastructure, ...
- Bottom
 - Solve specific problems, improve specific KPIs
- How much time we save/target?
- How much quality/yields we can increase/target?
- How much productivities we can improve/target?
- How much expense we have to spend/target?

Multi-objective optimization problem

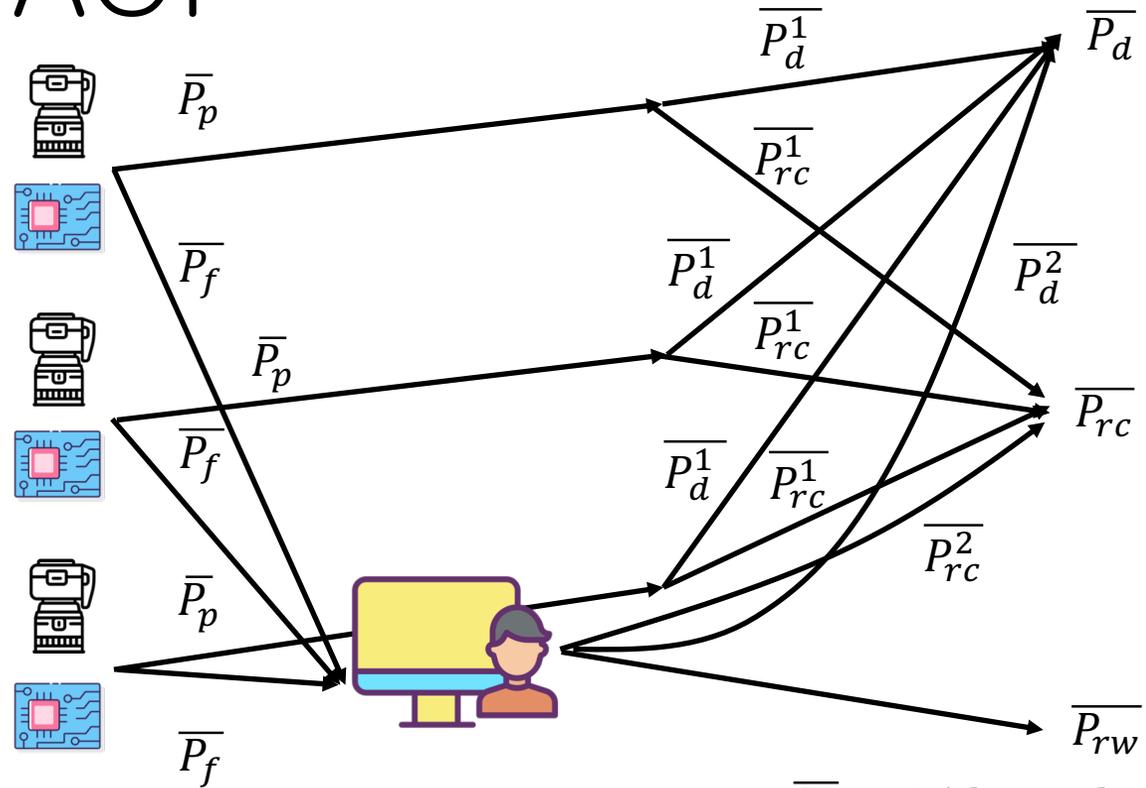
Conventional AOI



$$C_T = C_{HR} + C_E + C_{RC} + C_{RW}$$

$$D_T = P_d \cdot D_d + P_{rw} \cdot D_{rw}$$

AI-based AOI



$$\overline{C}_T = \frac{C_{HR}}{N(\overline{P}_f)} + \overline{C}_E(class, algo, camera) + C_{RC}(\overline{P}_{rc}) + C_{RW}$$

$$\overline{D}_T = \overline{P}_d \cdot D_d + \overline{P}_{rw} \cdot D_{rw}$$

$$\overline{P}_f = \mathcal{L}(data, class, algo, camera)$$

$$\overline{P}_{rc} = \mathcal{H}(data, class, algo, camera)$$

$$\overline{P}_d = \mathcal{R}(data, class, algo, camera)$$

Try to formulate your AIoT multi-objective optimization problem

Next Question, How?

- Launch a POC/prototype project
 - Not for demo, to figure out these missing parameters
 - Sometimes, google can help you to pin down the ranges of parameters

$$\overline{P_f} = \mathcal{L}(\text{data}, \text{class}, \text{algo}, \text{camera})$$

$$\overline{P_{rc}} = \mathcal{H}(\text{data}, \text{class}, \text{algo}, \text{camera})$$

$$\overline{P_d} = \mathcal{R}(\text{data}, \text{class}, \text{algo}, \text{camera})$$

$$\overline{C_E}(\text{class}, \text{algo}, \text{camera})$$

This article has been accepted for inclusion in a future issue of this journal. Content is final as presented, with the exception of pagination.

IEEE TRANSACTIONS ON COMPONENTS, PACKAGING AND MANUFACTURING TECHNOLOGY

SMT Solder Joint Inspection via a Novel Cascaded Convolutional Neural Network

Nian Cai¹, Guandong Cen, Jixiu Wu, Feiyang Li, Han Wang, and Xindu Chen

Abstract—Due to the excellent self-learning learning, we propose a novel deep-learning-based inspect surface-mount technology (SMT) sold paper. In contrast to the state-of-the-art learning in which low-level features are extracted before method directly implements the inspection to level feature extraction, which is based on a convolutional neural network (CNN). Three kind different network parameters compose the pr CNN. First, one kind of CNN is employed to the regions of interest (ROIs) of SMT solder joint both the learned ROIs and the entire solder joint into the other two kinds of CNNs, respectively. I results are achieved by the learned cascaded C experiments indicate that our proposed method excellent inspection performance for SMT solder of the state-of-the-art methods.

Index Terms—Cascaded network, convolutional networks (CNNs), regions of interest (ROIs), surface mount technology (SMT) solder joint inspection, weighted

SMD Classification for Machine using Convolutional Neural Network

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Abstract—Because different inspection items are applied to different devices mounted on a printed circuit board (PCB), the types of devices need to be identified for an automatic PCB inspection. This study proposes a device classification method using a convolutional neural network (CNN), which is a deep learning technique. CNNs perform well in terms of image classification, and because many up-sampling methods have been recently proposed, such an approach is widely used for segmentation problems. The classification method proposed in the present study uses a CNN to extract and classify only the device regions from device images obtained from a PCB.

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SMD Defect Classification by Convolution Neural Network and PCB Image Transform

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Abstract—Surface Mount Technology (SMT) process in which chips are mounted on printed circuit board (PCB). The automatic system (AOI) has mainly used the learning the defect classification of the SMT process CNN-based classification method has appeared techniques do not consider the area margin uneven color distribution according to the position so the classification accuracy decreases. In this study, we propose a system that can extract the chip region and distribution by the input image transformation system for PCBs. The proposed system distinguishes regions from the background in an input device extracts only the device regions, thereby classifying As shown in Figure 2, a PCB includes not only device silk screens and circuit patterns, and different materials adopt different PCB colors, silk screens, and circuit patterns. Because these elements are adjacent to the device

A VGG-16 based Faster RCNN Model for PCB Error Inspection in Industrial AOI Applications

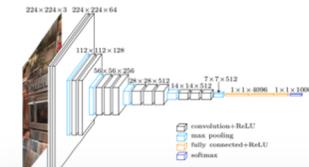
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Abstract— To detect product error and modify the product error, most industry are using human eyes. However, it is not only costs time but also costs money. Our purpose is to develop a model to detect the PCB board errors and draw the bounding boxes. The model is going to be developed with a pre-trained model VGG16 and data collected from Advantech corp. The error types of training data have been separated into five error types (Bridge, Appearance, Empty, Solder_ball, Solder_balls), where the highest AP result of these classes is over 90%.

I. INTRODUCTION

PCB error detection is a very important issue to modern industry. The PCB error detection in modern factory is human eyes which not only takes lots of time but also costs a lot. Most papers have studied at PCB layout defect detection[1]. Because of the lack of data, seldom papers study on PCB board detection[2]. Our purpose is to develop a deep learning model to detect the PCB board errors and draw the bounding boxes.

To develop a deep learning model with error detection and bounding box position detection, we choose the Faster RCNN developed by UC Berkeley, which has inserted a region proposal network (RPN) after the last convolutional layer. This network is able to just look at the last convolutional feature map and produce region proposals from that. The models of convolutional layers we used is VGG16 [3-4], which has 13 layers with ReLU, Max pooling, and 3 fully connected layers, as shown in Figure 3.



How to Get Started?



Around 20% of AIoT services have well-structured formula and well-known parameters

Determine these critical problems

Internalization

Yell for help

Is that easy or difficult?

Easy because

AIoT =

An Integration of old Technologies

KISS principle works well in AIoT area

Difficult because

AIoT =

An Innovation of Thinking

We not merely replace human intelligences by machine intelligences

We further redefine the manufacturing by machine intelligences

Summary

- Review FAQs for AIoT from a different perspective, i.e. Why, ~~How~~ and ~~What~~ for your AIoT investment
- Why: formulate multi-objective optimization problem for your AIoT project
- How: POCs to figure out the critical parameters rather a fancy demo
- How to get started
 - DIY: determine, leverage, internalized
 - An Integration of old Technologies: KISS principles
 - An Innovation of Thinking: not only replace but also redefine